



JP3293121

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## LAMINATE SUITABLE FOR HIGH FREQUENCY INDUCTION HEATING

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### Abstract

**PURPOSE:** To facilitate the controlling of heat sealing conditions by a method wherein thin metal film layer is provided at the position corresponding to the part necessary for heat of heat sealing layer made of thermoplastic synthetic resin.

**CONSTITUTION:** In the laminate 1 concerned, thin metal film layer 3 is provided at the position necessary for heating such as the position corresponding to the mouth of a container on heat sealing layer 2 made of thermoplastic synthetic resin film. Or, since the enough heating of only the layer 3 part is necessary by arranging the heat sealing layer 2 and the metal as described above, the controlling of heating conditions becomes easy and, at the same time, sure heat sealing can be realized. Or electrically conducting chip-containing resin layer 4 is provided between the thin film layer 3 and the heat sealing layer 2 so as to allow to serve as auxiliary heat generating layer without melting the heat sealing layer 2 and to cover the shortage of the amount of heat generating in the thin metal film layer 3.

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ヒートシールを行なうことができるなどの優れた効果がある。

#### 4. 図面の簡単な説明

第1図はこの発明に係る積層体の一実施例を示す断面図、第2図は第2の発明に係る積層体の一実施例を示す断面図、第3図乃至第5図は積層体の種々の実施例を示す断面図、第6図はヒートシールの状態を示す断面図である。

- 1……積層体、 2……ヒートシール層、
- 3……金属薄膜層、
- 4……導電性細片を含む樹脂層、
- 5、5'……保護層、 6……基材、
- 7……接着剤層、 10……容器、
- 11……容器の口部、
- 20……高周波誘導加熱コイル。

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